

The Full Spectrum of AOI Solutions

Diced Wafer Inspection - 850 DW

The 850G DW provides a high speed, high performance, fully integrated Diced Wafer inspection solution. Capable of delivering an inspection potential of up to 12, 300mm Diced Wafers per hour the 850 DW meets the demands for the highest of throughputs.

Introducing MVP's integrated handling solutions the 850 DW can be configured with a single controller for loading, inspection and unloading actions and supports full touchless recovery. Alternative manual loading solutions are available. MVP supply an integrated vacuum chuck configurable for multiple wafer sizes. Configurable electro-optic solutions provide performance inspection capabilities and full metrology capability.

The 850 DW also provides for full process integration with downstream processes including defect maps and also comes with full Management Webreports generated by MVP's AutoNetworker.

Integrated Film Frame Wafer Handler, Single Side Loading, Automated or Manual

Integrated MVP Vacuum Support Plate

Ease of Use Inspection Recipe Generation from

SECS-GEM Compliant

100 to 300mm Wafer Support

Standard Wafers and Multi Project Wafers Supported

Ink Marking Option or XML Defect Mapping Option

Custom Reports from Integrated AutoNetworker

Class 100 clean room option

Die Metrology and Edge Inspection

Die Surface Inspection for Scratches, Contamination and FM



* Model material handling input differs from image shown

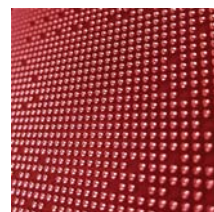
Discuss your Microelectronics and SMT inspection application with Machine Vision Products, Inc and discover your solution



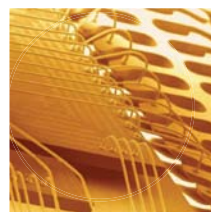
SMT AOI



3D Paste AOI



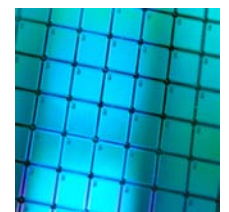
BGA AOI



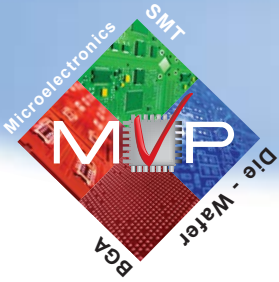
Wire Bond AOI



Die and Epoxy AOI



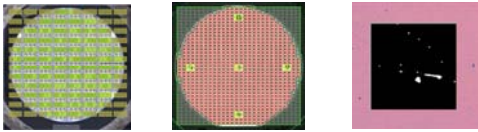
Die Surface AOI



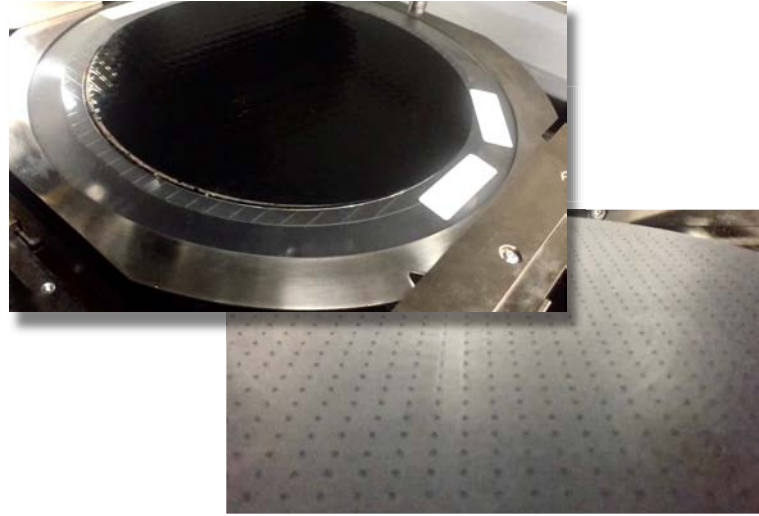
- Inspection Speed**
- Acquisition Speed of 75 Megapixels per Second with a Single 5MP or 8MP Camera
 - 8-15 wafer UPH

- System Hardware**
- High Measurement Accuracy Stage
 - State-of-the-art Large Format Color Camera
 - Proprietary "On-the-fly" Camera Acquisition
 - Programmable Variable LED Strobe Lighting
 - Proprietary Multi-color Illumination
 - Field of View, Resolution, 1.7 Micron/Pixel
 - Copy-exact, Inter-machine Capability
 - MVP Intergrated and Configurable Vacuum

- System Software**
- Ease of Use Wafer Generation with Library-based Software



- Proven High Performance, Adaptable Algorithms with Highest Detectability
- Lowest False Accept & False Reject Rates
- Full Network Integration (TCP/IP, NFS Protocol)
- Off-line or In-line Defect Review Capability
- Defect Image Archive Capability
- Real-time SPC Package and XML Reports
- Report Generation Utilities for Production Inspection Measurements
- Inspection Program Change Tracking
- On-the-fly Unit Level and Carrier Tracking with 2D Matrix Reader
- 5th Generation Proven Inspection Software
- Multi-pass Technology, Adjustable Lighting Intensity
- Multi-substrate Step and Repeat Programming and Inspection Capability



- Material Handling**
- Modular Wafer Handling Options
 - SMEMA Interface
 - Auto Wafer Clamp for Precision Registration
 - Vacuum Table



- Physical Specification**
- Inspection Envelope 300 x 300mm (12 x 12")
 - Footprint 844 x 1066mm (33.25 x 42")
 - Height 1473mm (58")
 - Conveyor Length 850mm (33.46")
 - Power 220-240VAC 50/60Hz 10 Amperes
 - Air 60 PSI, 1CFM
 - Weight 680kgs (1500 lbs)

- Options**
- SECS/GEM Interface
 - CAD Translation Software
 - Offline Programming Capability
 - MVP Dynamic Process Control
 - MVP AutoNetworker and Web Reporting

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